

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ICHIRO SHIMIZU	07/04/2019
AKIRA WADA	07/04/2019
MAKOTO SASAKI	07/04/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16525123
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NAME OF SUBMITTER:	BETHANY LICHTSCHEIDL
SIGNATURE:	/Bethany Lichtscheidl/
DATE SIGNED:	07/29/2019
Total Attachments: 2 source=NNS0008US_Assignment#page1.tif source=NNS0008US_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I/WE, SHIMIZU, Ichiro, Japan;
WADA, Akira, Japan; and
SASAKI, Makoto, Japan;

have invented certain new and useful improvements in

BIOABSORBABLE STENT

WHEREAS, KAKE EDUCATIONAL INSTITUTION OKAYAMA UNIVERSITY OF SCIENCE
of 1-1, Ridai-cho, Kita-ku, Okayama-shi, OKAYAMA 700-0005 JAPAN

and Japan Medical Device Technology Co., Ltd.

of 2020-3-D, Oaza Tabaru, Mashiki-machi, Kamimashiki-gun, KUMAMOTO 861-2202 JAPAN
(hereafter "Assignee");

are desirous of acquiring the entire right, title and interest in and to said invention, said application
and in, to and under any and all Letters Patent to be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby
acknowledged, I/we have sold, assigned and transferred, and by these presents do hereby sell, assign
and transfer unto the said Assignee, its successors and assigns, the entire right, title and interest in
and to said invention, said application and the Letters Patent, both foreign and domestic, that may or
shall issue, including all rights under any applicable International Convention, and I/we do hereby
expressly authorize and request the United States Commissioner for Patents to issue said Letters
Patent to the above-mentioned assignee in accordance herewith.

I/We further authorize said assignee, its successors and assigns, or anyone it may properly
designate, to apply for Letters Patent, in its own name, if desired, in any and all countries, and
additionally to claim the filing date of said application filed corresponding to this Invention and any
appropriate priority claim and/or otherwise take advantage of the provisions of any applicable
International Convention.

I/We do hereby covenant and agree with the said assignee, its successors and assigns, that
I/we will not execute any writing or do any act whatsoever conflicting with these presents, and that
I/we or our executors or administrators will, at any time upon request, without further or additional
consideration, but at the expense of said assignee, its successors and assigns, execute such additional
writings and do such additional acts as said assignee, its successors and assigns, may deem necessary
or desirable to perfect the assignee's enjoyment of this grant, and render all necessary assistance in
making application for and obtaining original, divisional, continuing, reissued or extended Letters
Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any
rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or
transactions involving such applications or patents.

In Witness Whereof, I/we have hereunto set our hands on the date(s) written below.

Signature

I. Shimizu

Date July 4, 2019

Name

SHIMIZU, Ichiro

Signature WADA Akira Date July 4, 2019
Name WADA, Akira

Signature SASAKI Makoto Date July 4, 2019
Name SASAKI, Makoto